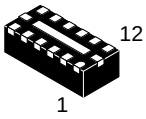
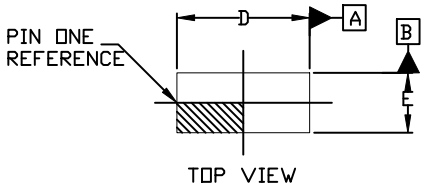
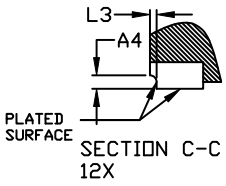


DFNW12 3x1.35, 0.5P
CASE 507AY
ISSUE O

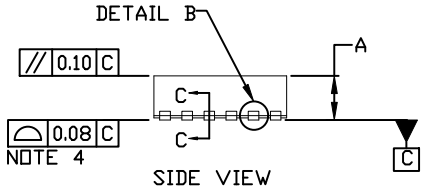
DATE 13 JUN 2019

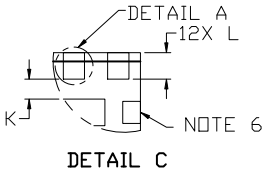


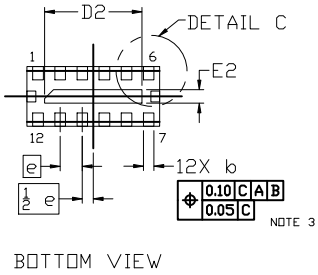


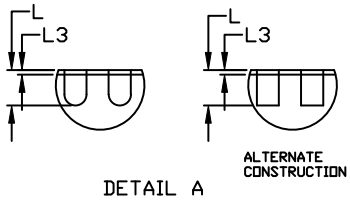
NOTES:

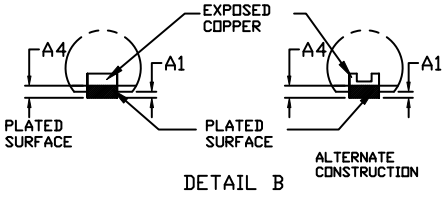
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.
6. EXPOSED PADS CONNECTED TO DIE FLAG USED AS TEST CONTACTS. SIZE (0.20 X 0.25mm)





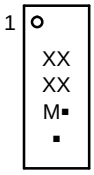






DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	---	0.05
A3	0.20 REF		
A4	0.10	---	---
b	0.18	0.24	0.30
D	2.85	3.00	3.15
D2	2.10	2.20	2.30
E	1.20	1.35	1.50
E2	0.20	0.30	0.40
e	0.50 BSC		
K	0.20	---	---
L	0.20	0.30	0.40
L3	---	---	0.10

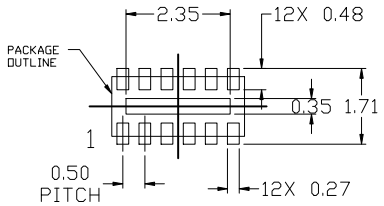
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	**98AON08530H**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**DFNW12 3x1.35, 0.5P**		**PAGE 1 OF 1**